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Okajima et al.

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(54) **COVER OF SEAL CAP FOR REACTION CHAMBER OF SEMICONDUCTOR**

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(**) Term: **15 Years**

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(51) **LOC (11) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/182, 184, 162; D10/49, 50
CPC C23C 16/455; C23C 16/45502; C23C 16/45517; C23C 16/4582; C23C 16/4583; C23C 16/4584; C23C 16/4585; C23C 16/4401; C23C 16/4402; C23C 16/4409; H01L 21/50; H01L 21/4817; H01L 21/4871; H01L 23/02; H01L 23/04; H01L 23/12; H01L 23/13; H01L 23/14; H05K 3/30

See application file for complete search history.

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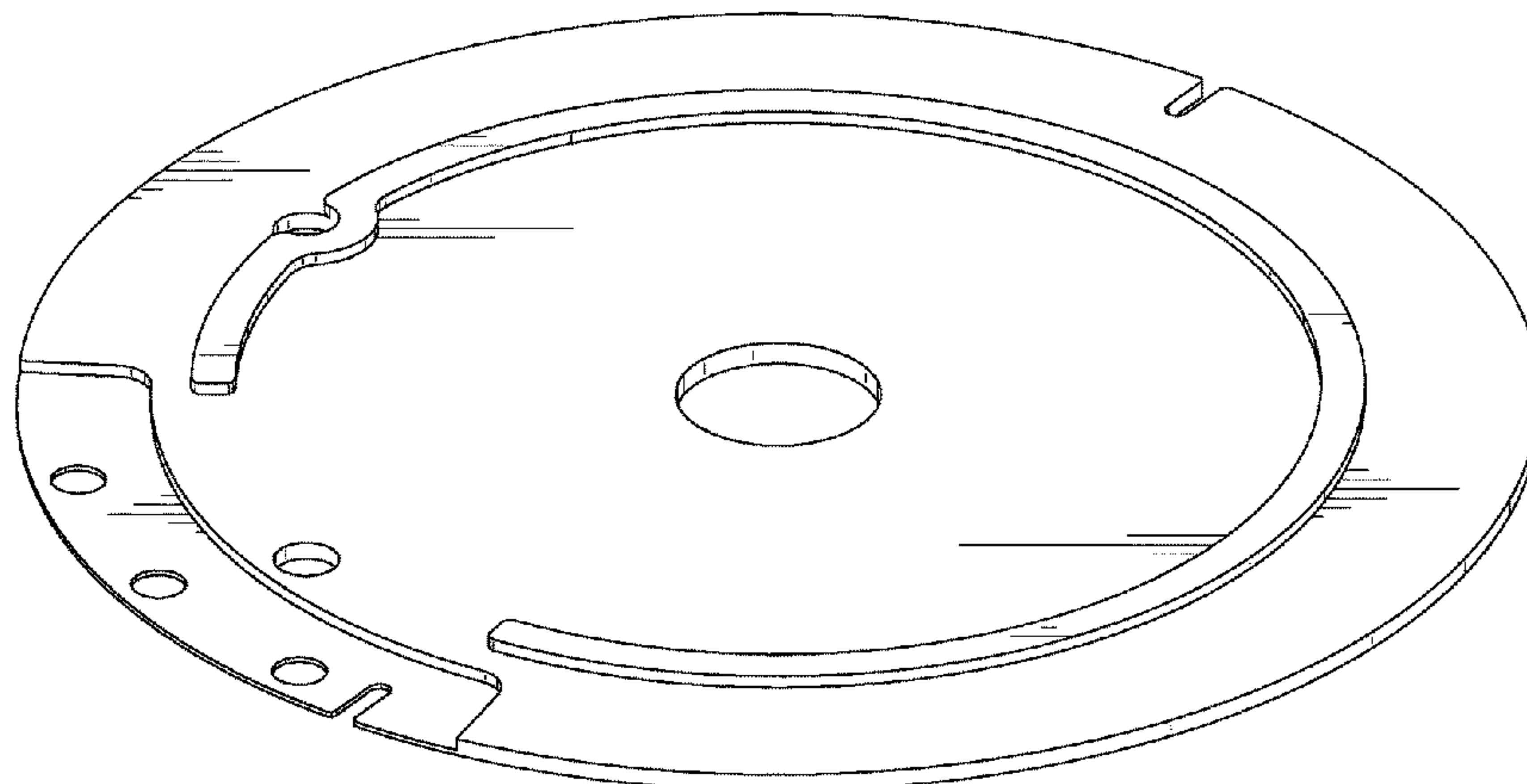
(57) **CLAIM**

The ornamental design for a cover of seal cap for reaction chamber of semiconductor, as shown and described.

DESCRIPTION

FIG. 1 is a front, top and right side perspective view of a cover of seal cap for reaction chamber of semiconductor showing my new design;
FIG. 2 is a top plan view thereof;
FIG. 3 is a bottom plan view thereof;
FIG. 4 is a front elevational view thereof;
FIG. 5 is a rear elevational view thereof;
FIG. 6 is a right side elevational view thereof;
FIG. 7 is a left side elevational view; and,
FIG. 8 is a cross-sectional view take along line 8-8 in FIG. 4.

1 Claim, 4 Drawing Sheets



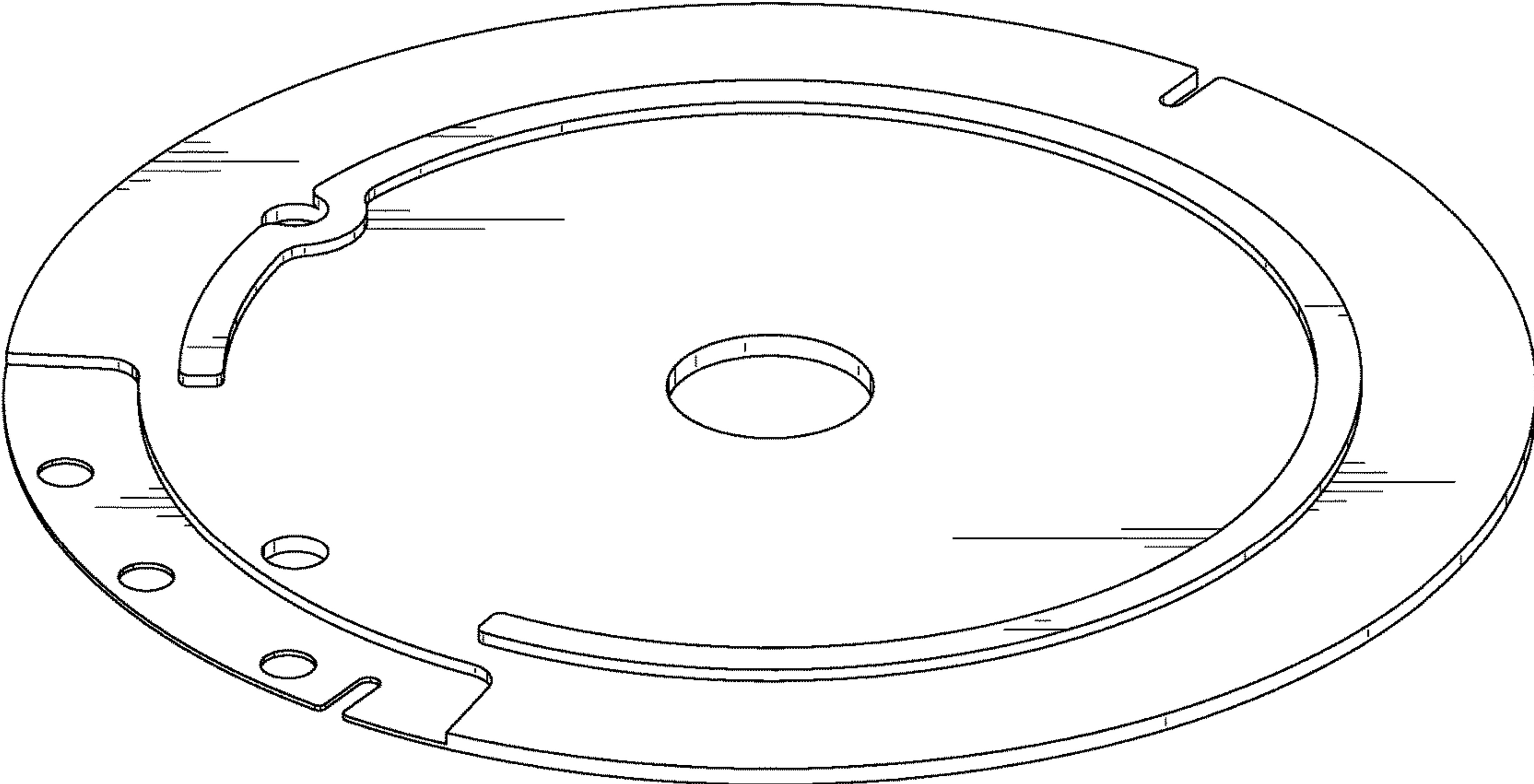


FIG. 1

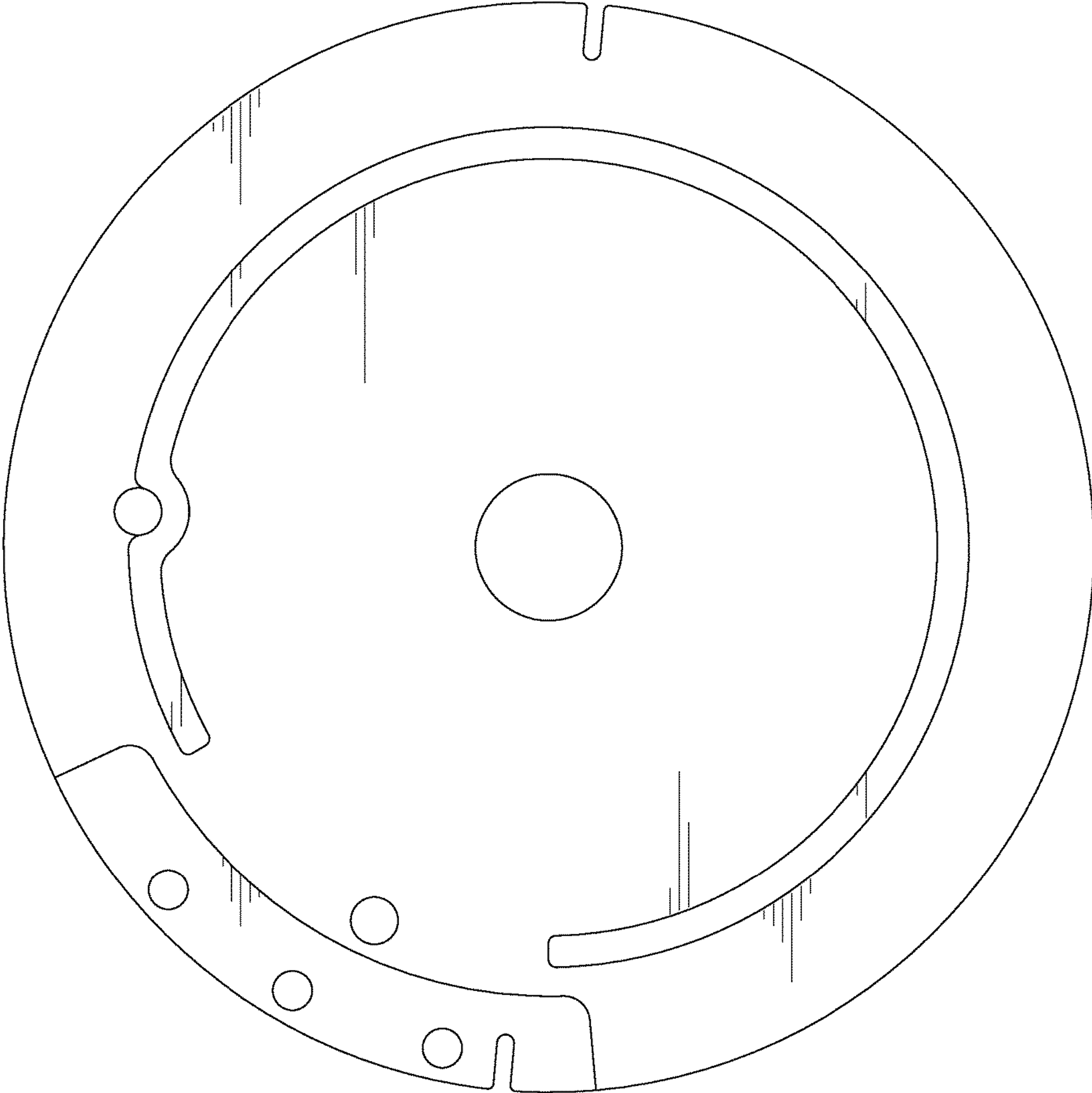


FIG. 2

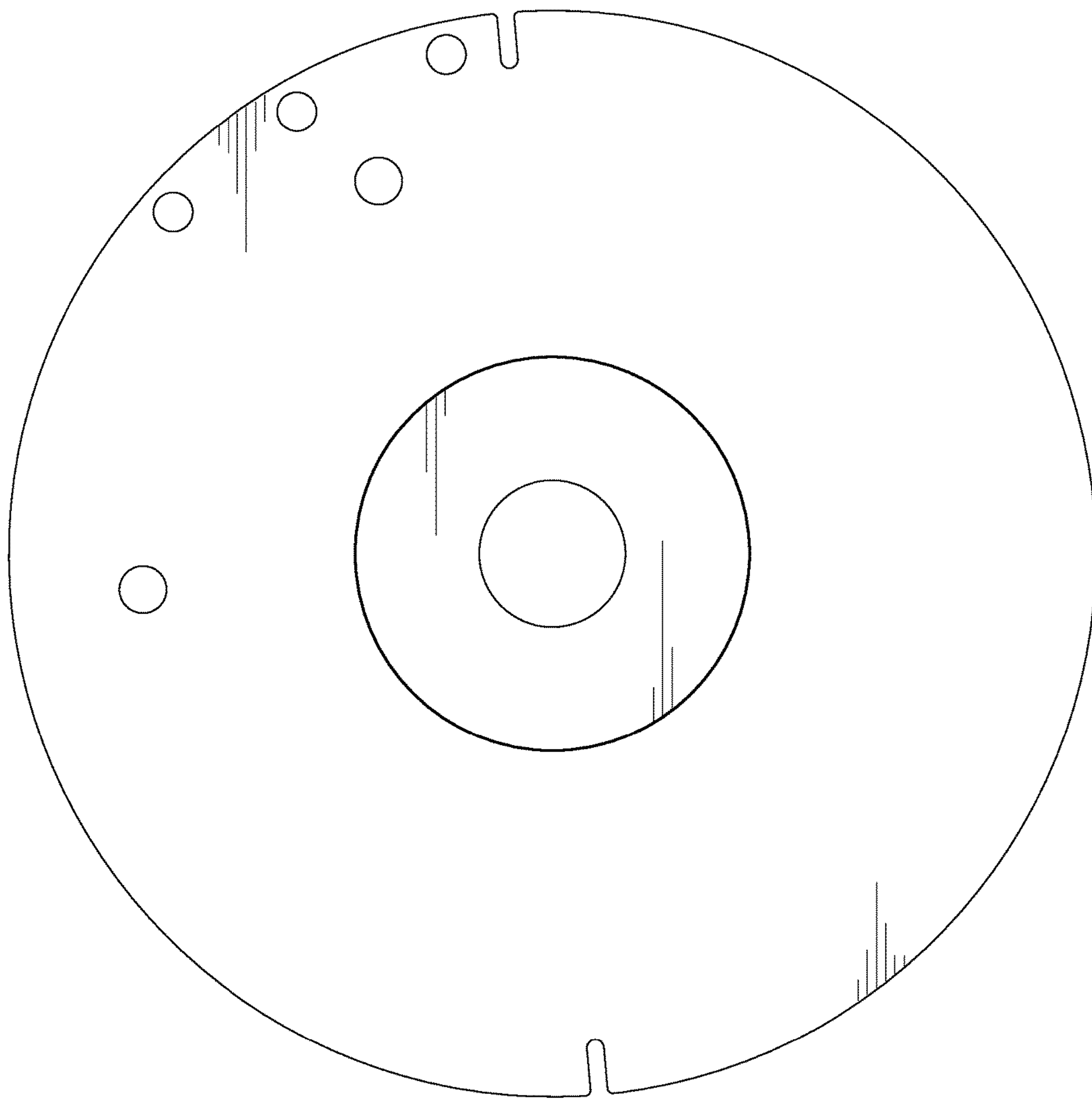
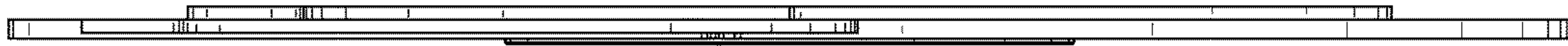


FIG. 3

8 ←



8 ←

FIG. 4



FIG. 5



FIG. 6



FIG. 7

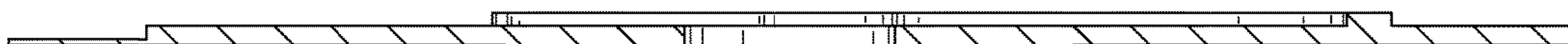


FIG. 8